

N-Channel Enhancement Mode MOSFET

1. Product Information

Features

SGT technology
Excellent RDS(ON)
Low gate charge

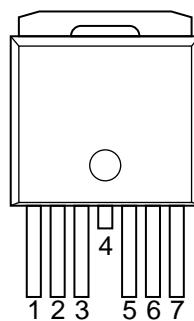
Pin Description

Pin	Description
1	Gate(G)
4	Drain(D)
2,3,5,6,7	Source(S)

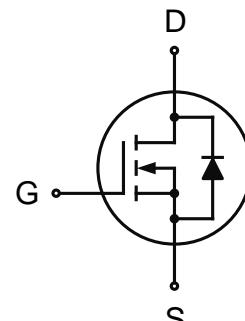
Applications

BMS
UPS
Power management Switches

Simplified Outline



Symbol



Top View
TO-263-7L

Quick reference

$V_{DS} = 120V$
 $I_D = 240A$
 $R_{DS(ON)} \leq 4.2 \text{ m}\Omega @ V_{GS}=10V$ (Type: 3.7mΩ)

Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape width	Quantity
KJ037N12D7	TO-263-7L	KJ037N12D7	-	-	800

2. Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	120	V
VGS	Gate-Source Voltage	± 20	V
$I_D @ T_c=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V$	240	A
$I_D @ T_c=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V$	180	A
IDM	Pulsed Drain Current	360	A
EAS	Single Pulse Avalanche Energy	530	mJ
IAS	Avalanche Current	45	A
$P_D @ T_c=25^\circ\text{C}$	Total Power Dissipation ⁴	240	W
TSTG	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	0.75	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	62	°C/W

3. Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Type	Max.	Unit
VDSS	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu\text{A}$	120	135	-	V
IGSS	Gate-body Leakage current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
IDSS	Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$V_{DS} = 120V, V_{GS} = 0V$	-	-	1	μA
IDSS	Zero Gate Voltage Drain Current $T_J=100^\circ\text{C}$		-	-	100	
VGS(th)	Gate-Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	2.9	4.0	V
RDS(on)	Drain-Source on-Resistance ²	$V_{GS} = 10V, I_D = 20A$	-	3.7	4.2	$\text{m}\Omega$
RDS(on)	Drain-Source on-Resistance ²	$V_{GS} = 6V, I_D = 20A$		4.3	5.8	$\text{m}\Omega$
Ciss	Input Capacitance	VGS = 0V, VDS = 60V, f = 250kHz	-	5240	-	pF
Coss	Output Capacitance		-	739	-	
Crss	Reverse Transfer Capacitance		-	12	-	
Rg	Gate Resistance	$V_{GS} = 0V, V_{DS} = 0V, f = 1\text{MHz}$	-	1.7	-	Ω
Qg	Total Gate Charge	VDD = 60V, ID = 45A, VGS = 0 to 10V	-	19	-	nC
Qgs	Gate-Source Charge		-	11	-	
Qgd	Gate-Drain Charge		-	75	-	
td(on)	Turn-on Delay Time	VDD = 60V, VGS = 10V, ID = 45A, RG = 10 Ω	-	59	-	ns
t _r	Rise Time		-	41	-	
td(off)	Turn-off Delay Time		-	96	-	
t _f	Fall Time		-	33	-	
VSD	Diode Forward Voltage ²	$I_F = 20A, V_{GS} = 0V$	-	0.8	1.2	V
IS	Continuous Source Current ^{1,5}	$V_G = V_D = 0V$, Force Current	-	-	200	A
trr	Body Diode Reverse Recovery Time	VR = 60V $I_F = 35A$, dI/dt = 100A/ μs	-	70	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	200	-	nC

Notes:

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $V_{DD}=50V$, $V_{GS}=10V$, $L=0.5\text{mH}$, $I_{AS}=45A$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

4. Typical Characteristics

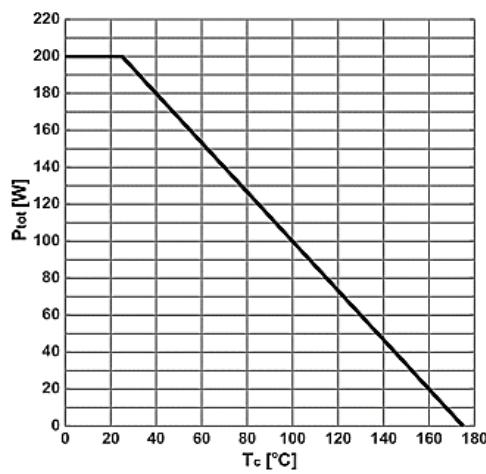


Figure 1. Power dissipation

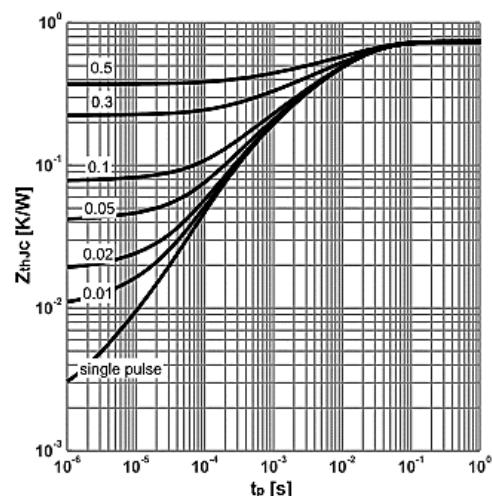


Figure 2. Max. transient thermal impedance

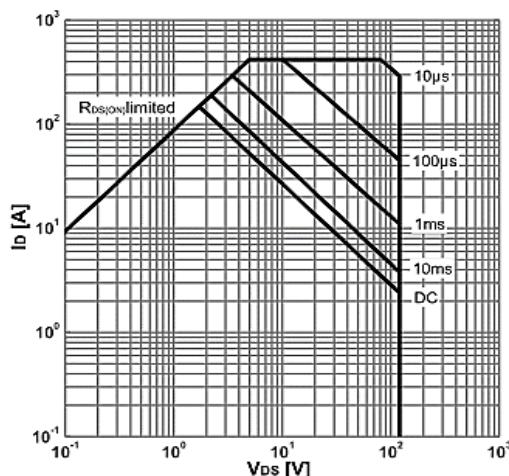


Figure 3. Safe operating area

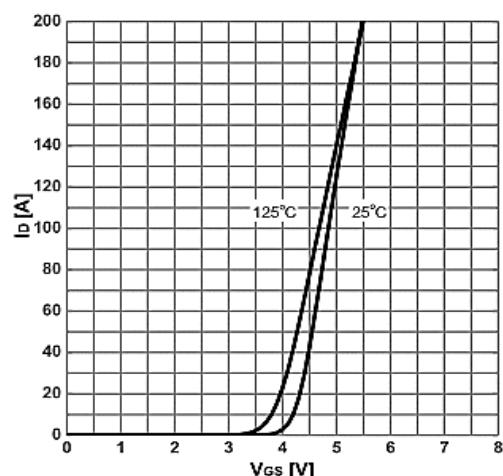


Figure 4. Type. transfer characteristics

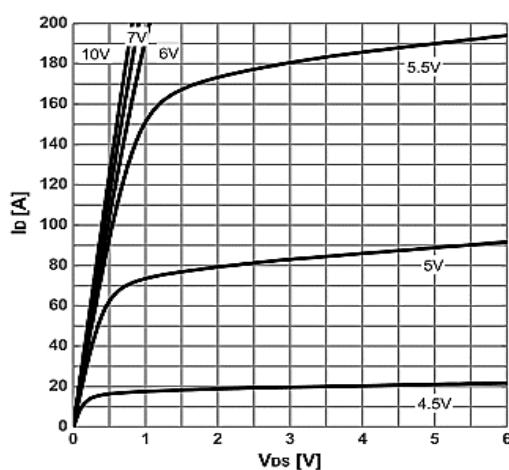


Figure 5. Typ. output characteristics(Tj 25°C)

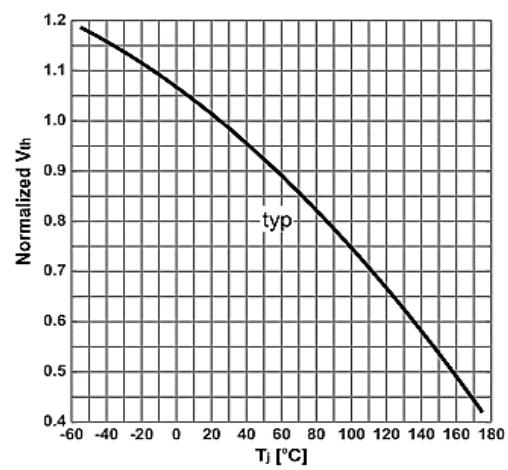


Figure 6. Typ. output characteristics(Tj 125°C)

4. Typical Characteristics (cont.)

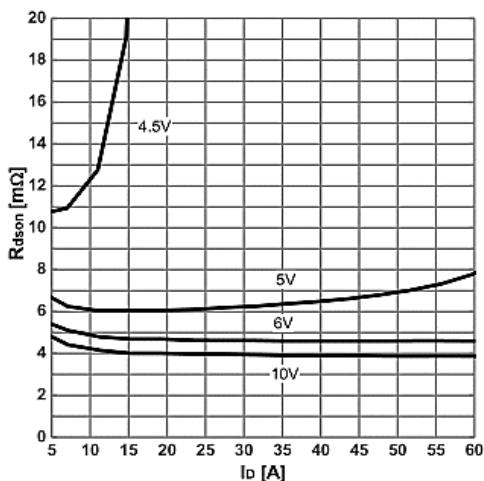


Figure 7. On-state resistance vs. Drain current

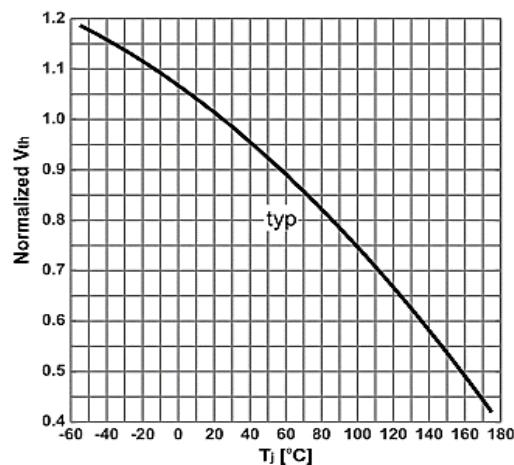


Figure 6. Gate threshold voltage vs. Junction Temperature

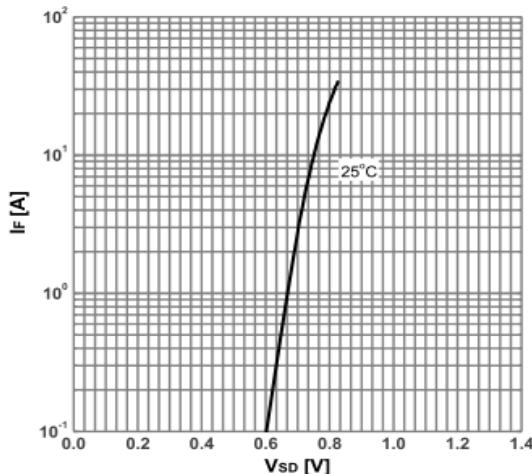


Figure 9. Forward characteristics of reverse diode

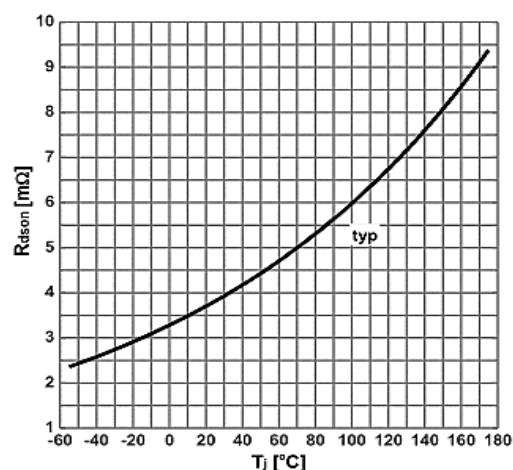


Figure 8. On-state resistance vs. Junctiontemperature

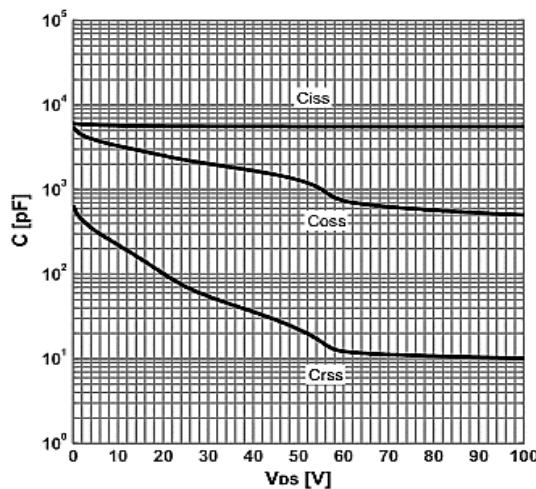


Figure9 Typ. capacitances

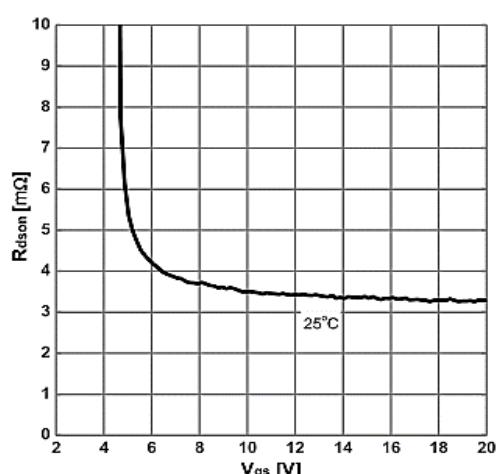


Figure11. On-state resistance vs. Vgs characteristics

4. Typical Characteristics (cont.)

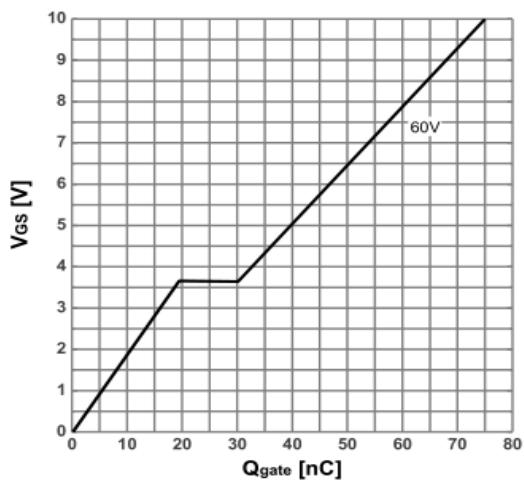
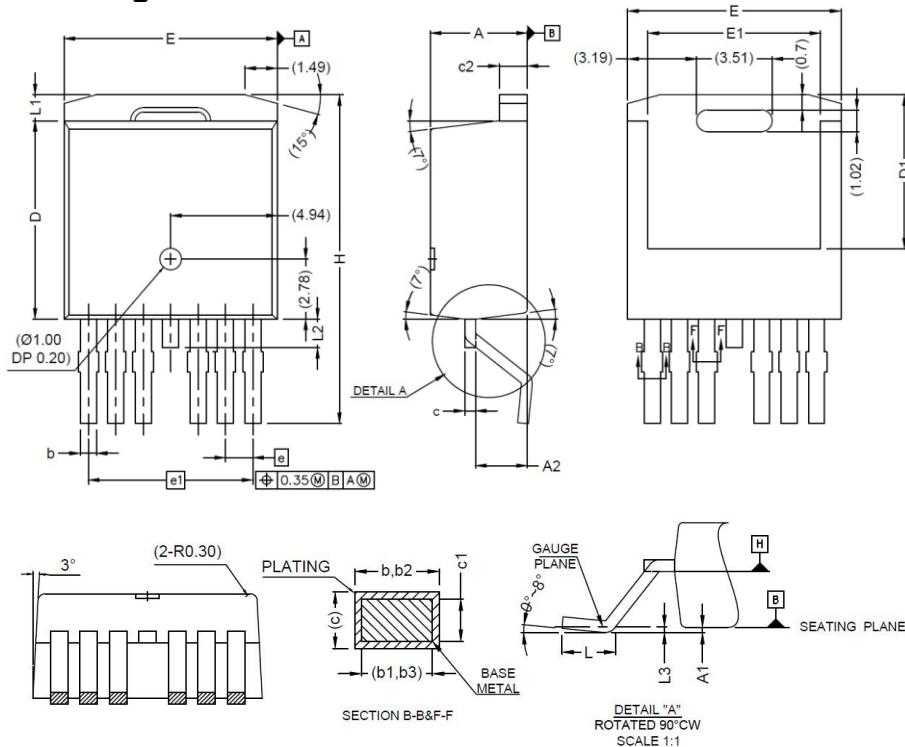


Figure 13: Typ. gate charge

5. Package Mechanical Data

TO-263-7L Package



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	4.30	4.70
A1	-	0.25
A2	2.20	2.60
b	0.65	0.85
b1	0.65	0.80
b2	0.80	1.00
b3	0.80	0.95
c	0.45	0.60
c1	0.45	0.55
c2	1.25	1.40
D	9.00	9.40
D1	6.86	7.42
E	9.68	10.08
E1	7.70	8.30
e	1.27 BSC	
e1	7.62 BSC	
L	1.78	2.79
L1	-	1.60
L2	-	1.78
L3	0.25 BSD	
H	14.61	15.88